ASOCIATION CONNECTING ELECTRONICS INDUSTRIES® international and Pan	C. Bannockl	burn. Illinois. A	ll rights reserved untions.	under both	This docum level parts, t	ent is a declara	tion of the s encompasse	substances es all lowe	within the 1 r level mate	manufacture rials for wh	er listed iten ich the man	n. Note: if ufacturer	the item is an as has engineering	sembly with lower responsibility.
	IPC Web Site for Information on IPC-1752 Standard Form http://www.ipc.org/IPC-175x Distr				* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi					ous Materia	als and Mfg Information			
Supplier Information														
Company name* Co			Company unique ID			Unique ID Authority					Response Date*			
nsemi											2025-06-07			
ontact Name Title - Contact			ct			Phone - Contact*					Email - Contact*			
Product-Env-Stewards Product 1			luct Enviro Compliance			NA				Product-Env-Stewards@onsemi.com				
Authorized Representative* Title - Repres			esentative			Phone - Representative*				Email - Representative*				
Product-Env-Stewards Produ			roduct Enviro Compliance			NA				Product-Env-Stewards@onsemi.com				
Requester Item Number	Mfr Iten	n Number	Mfr Item Name			Effective Dat	e Version		Manufacturing Site		We	ight*	UOM	Unit Type
	NCP302 G	CP302155RMNTW 50A Smart Powe		Stage Module		2025-06-07		:	РВВ		73.	67428	mg	Each
Manufacturing Proccess Informat	ion													
Terminal Plating / Grid Array Ma	terial 7	rial Terminal Base Alloy		J-STD-020 MSI	TD-020 MSL Rating		Peak Process Body Temperatu		ure Max Time at Peak Temper		Femperature	Numb	er of Reflow Cyc	cles
Matte Tin (Sn) - annealed CU Alloy			1		260		C	30		seconds	3			
Comments														
evel 1 - maximum time at peak temperatu	re during so	ldering is 10-3	0 seconds											
For more information regarding material of	omposition	please refer to	page 3											

RoHS Material Composition Declaration				Declaration Type *	Detailed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Disobutyl phthalate (DIBP).										
cadmium, hexavalentchromium, polybromina contains a RoHS restricted substance inexces encompass all such components. Supplier cer as of the date that Supplier completes this for Company acknowledges that Supplier may h independently verified information provided certification in this paragraph. If the Company	ated biphenyls and/or polybrominated dip s of an applicable quantity limit, please in iffies that it gathered the information it pr m.Supplier acknowledges that Company ave relied on informationprovided by oth by others, Supplier agrees that, at a minir and the Supplier enter into a written agr esource of the Supplier's liability and the	henyl ethers (each a "RoHS restricted substa ndicate below which, if any, RoHS exemption ovides in this form using appropriate methoo will rely on this certification in determining ers in completing this form, and that Supplie num, itssuppliers have provided certification eement with respect to the identified part, the Company's remedies for issues that arise reg	nce") in exco n you believe ls to ensure i the compliar r may not ha s regarding t terms and co	e may apply. If the part is an assembly with low s accuracy and that such information is true an ce of its products with European Union member de independently verified such information. Ho neir contributions to the part, and those certifica	ove. If a homogeneous material within the part er level components, the declaration shall d correct to the best of its knowledge and belief, er state laws that implement the RoHS Directive. wever, in situations where Supplier has not ations are at least as comprehensive as the anty rights and/or remedies provided as part of						
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted subst	ances per the definition above except for sele	ected exempt	ions Supplier Acceptance	* Accepted						
Exemption: 7a: Lead in high melting temp	erature type solders (i.e. lead based sol	der alloys containing 85% by weight or m	ore lead).								
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructions: Complete all of the required Requester) and click on Submit Form to h			e drop-dowi	a. This will display the signature area. Digita	lly sign the declaration (if required by the						
Supplier Digital Signature	astislav Drska	Le									

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Clip	6.34295	mg	Supplier	Zinc (Zn)	7440-66-6		0.0076	mg
			Supplier	Iron (Fe)	7439-89-6		0.1491	mg
			Supplier	Copper (Cu)	7440-50-8		6.1844	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0019	mg
Die	0.317142	mg	Supplier	Silicon (Si)	7440-21-3		0.3171	mg
Die Attach Solder	2.17762	mg	Supplier	Silver (Ag)	7440-22-4		0.0544	mg
			А	Lead (Pb)	7439-92-1	7a	2.0143	mg
			Supplier	Tin (Sn)	7440-31-5		0.1089	mg
Epoxy	0.1291	mg	Supplier	Titanium Dioxide (TiO2)	13463-67-7		0.0116	mg
			Supplier	Proprietary	Proprietary Data		0.0007	mg
			Supplier	Bismaleimide	13676-54-5		0.0651	mg
			Supplier	PTFE	9002-84-0		0.0516	mg
Lead Frame	31.0723	mg	Supplier	Silver (Ag)	7440-22-4		1.5538	mg
			Supplier	Zinc (Zn)	7440-66-6		0.0373	mg
			Supplier	Iron (Fe)	7439-89-6		0.7458	mg
			Supplier	Copper (Cu)	7440-50-8		28.7106	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0249	mg
Mold Compound-Black	31.2746	mg		Epoxy resin	proprietary data		4.1595	mg
			Supplier	Carbon Black (C)	1333-86-4		0.0625	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		27.0525	mg
Plating	2.10085	mg	Supplier	Tin (Sn)	7440-31-5		2.1009	mg
Wire Bond - Cu	0.259717	mg	Supplier	Palladium (Pd)	7440-05-3		0.0047	mg
			Supplier	Gold (Au)	7440-57-5		0.0003	mg
			Supplier	Copper (Cu)	7440-50-8		0.2548	mg